

Overview

The purpose of this notification is to communicate that Xilinx is changing the lid size used on the XQR5VFX130-1CF1752V and B grade products. In addition Xilinx will be changing at a later date the lid sizes used for the XQR4VFX60-10CF1144V, XQR4VSX55-10CF1140V, XQR4VLX200-10CF1509V and the XQR4VFX140-10CF1509V products.

Description

Xilinx is currently shipping the XQR5VFX130-1CF1752V and B grade products with a lid size of 32 x 25 x 2 mm. This lid only covers the die, exposing the chip capacitors. The exposed chip capacitors may potentially be mechanically damaged by mishandling. Xilinx has decided to convert the current lid to a larger size lid (38.5 x 38.5 x 2 mm) for the XQR5VFX130-1CF1752V and B grades products to cover and protect the capacitors.

In addition, Xilinx will also convert the Virtex[®]-4 QV FPGA CF package products to larger lid sizes to cover the chip capacitors. The existing Virtex-4 and Virtex[®]-5 QV FPGA products are highly reliable when handled with care, this lid modification is to further enhance the package use ability. Current inventory will continue to ship until depleted. Handling guidelines can be found in [UG496](#) (Virtex-4 QV FPGA Ceramic Packaging and Pinout) and [UG520](#) (Virtex-5 QV FPGA Packaging and Pinout) at Xilinx.com.

This change will be aligned with our IBM assembly supplier standard CF package design. This change will not affect any of the material set. Note that the new lids will slightly increase the total weight of each device/package. The total device/package weight increase should not exceed approximately 5 grams.

Products Affected

This change affects all speed, package, and temperature variations of the XQR V and B grade products. Affected part numbers are included in [Table 1](#), below.

Table 1: Product Changes

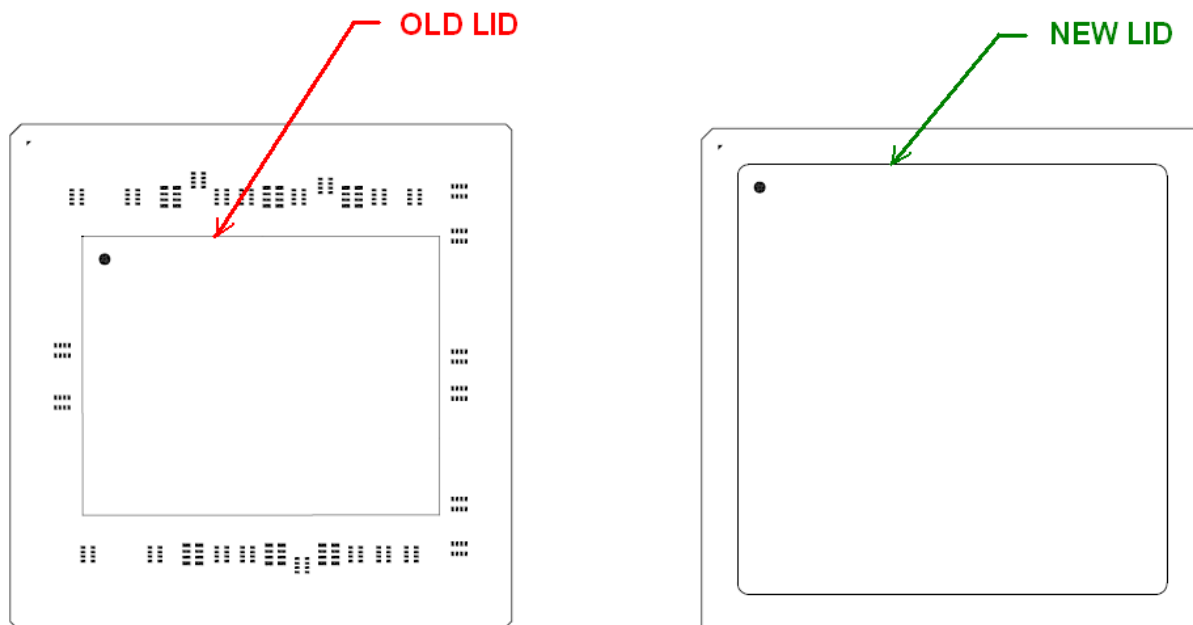
Xilinx Product
XQR5VFX130-1CF1752V
XQR5VFX130-1CF1752B
XQDAISY-CF1752
XQR4VFX60-10CF1144V
XQR4VSX55-10CF1140V
XQR4VLX200-10CF1509V
XQR4VFX140-10CF1509V
XCDAISY-CF1140
XCDAISY-CF1144
XCDAISY-CF1509

Key Dates and Ordering Information

This change is effective upon the release of this notification. Xilinx will begin to ship the XQR5VFX130-1CF1752V and B grade products with the new lid on all lots assembled with date code of 1240 or after. The new lids on the Virtex-4 QV FPGA product will be implemented with date codes of 1301 or after.

XQDAISY and XCDAISY with the new lid will be assembled on or before the date codes listed above.

FIGURE 1: CF1752 Lid Size Change



Qualification Data

Xilinx will perform a Group D qualification on every device/package lot assembled with the larger lids.

Response

No response is required. For additional information or questions, please contact your local sales representative.

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Revision History

The following table shows the revision history for this document:

Date	Version	Description of Revisions
9/10/12	1.0	Initial release.

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